COMPLETE LISTING OF CLAIMS

1.-4. (Cancelled)

5. (Currently Amended) A method for manufacturing a glass substrate for use in data recording media in which a polishing pad is used, the method comprising:

contacting the surface of a lapped glass workpiece with a polishing portion of the polishing pad with a load of 35 to 70 gf/cm^2 on the lapped glass workpiece, wherein said polishing portion is formed of a foam made of a synthetic resin having a 100% modulus of 11.8 MPa or less; and

polishing the lapped glass workpiece over a polishing period time in units of minute such that the product between the polishing period of time and said load in units of gf/cm^2 is 160 or more.

6. (Currently Amended) A method for manufacturing a glass substrate for use in data recording media, the method comprising:

lapping a glass workpiece by use of a hard pad and a polishing agent containing particles of about 1.2 μm in average particle size; and

polishing the glass workpiece obtained in said lapping by use of a polishing portion of a soft pad and a polishing agent containing particles of about 0.6 μm in average particle size, wherein said polishing portion has a surface roughness with a maximum height of 70 μm or less.

7. (Currently Amended) The method according to claim 6, wherein in said polishing the glass workpiece obtained, the polishing portion~~soft pad~~ is made to contact the glass workpiece with a load of 35 to 70 gf/cm^2 and the product between the load in units of gf/cm^2 and a polishing period of time in units of minute is 160 or more.

8. (Original) The method according to claim 6, wherein said lapping includes an amount of grinding of 30 to 40 μm.

9. (Original) The method according to claim 6, wherein said polishing of the glass workpiece obtained includes an amount of grinding of 0.5 to 10 μm.

10. (Original) A glass substrate for use in data recording media manufactured by the method according to claim 5, wherein:

the micro-waviness height is 0.3 nm or less measured by using a three dimensional surface structure analysis microscope, with the measurement wavelengths, λ, set to fall within the range from 0.18 to 0.40 mm.

11. (New) The method according to Claim 5, wherein said polishing portion has a surface roughness with a maximum height of 70 μm or less.

12. (New) The method according to Claim 6, wherein said polishing portion is formed of a foam made of a synthetic resin having a 100% modulus of 11.8 MPa or less.

13. (New) A method for manufacturing a glass substrate for use in data recording media, the method comprising:

contacting the surface of a lapped glass workpiece with a polishing portion of a polishing pad, wherein said polishing pad comprises a base and said polishing portion is laminated on a surface of said base, said polishing portion being formed of a foam made of a synthetic resin having a 100% modulus of 11.8 MPa or less and having a surface roughness with a maximum height of 70 μm or less; and

polishing said lapped glass workpiece.

14. (New) The method according to claim 13, wherein in said polishing said lapped glass workpiece there is a load of 35 to 70 gf/cm^2 on the lapped glass workpiece.

15. (New) The method according to claim 14, wherein said polishing said lapped glass workpiece comprises polishing said lapped glass workpiece over a polishing period of time in units of minutes such that the product between said load in units of gf/cm^2 and the polishing period of time in units of minute is 160 or more.

16. (New) The method according to Claim 13, wherein said polishing said lapped glass workpiece includes an amount of grinding of 0.5 to 10 μm.

17. (New) A glass substrate for use in data recording media manufactured by the method according to claim 13, wherein:

the micro-waviness height is 0.3 nm or less measured by using a three dimensional surface structure analysis microscope, with the measurement wavelengths, λ, set to fall within the range from 0.18 to 0.40 mm.